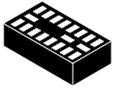


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

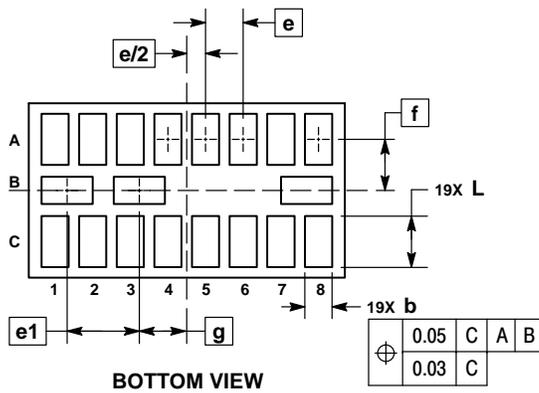
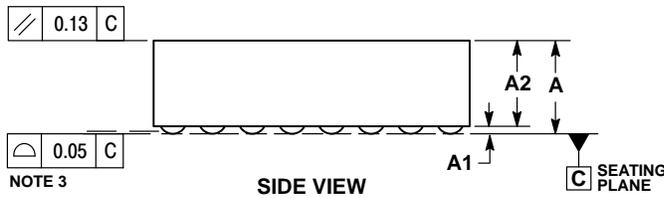
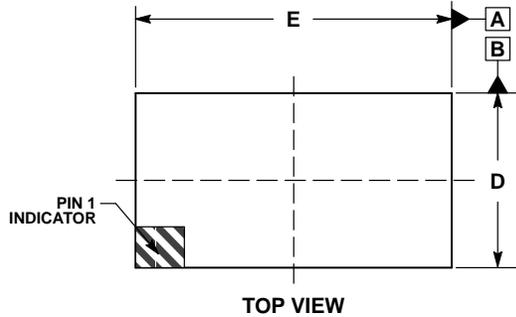
ON Semiconductor®



SCALE 2:1

SIP19 5.25x2.90
CASE 127ES
ISSUE B

DATE 01 DEC 2017

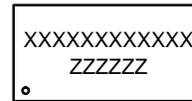


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BUMPS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	1.525
A1	0.060	0.125
A2	1.200	1.400
b	0.400	0.500
D	2.775	3.025
E	5.125	5.375
e	0.625 BSC	
e1	1.200 BSC	
f	0.850 BSC	
g	0.788 BSC	
L	0.800	0.900

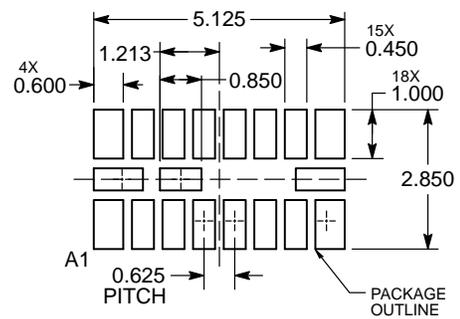
GENERIC MARKING DIAGRAM*



XX = Specific Device Code
ZZ = Assembly Lot

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "C" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	SIP19 5.25X2.90	PAGE 1 OF 2

